

ABSTRACT

A semiconductor device ~~is disclosed which is~~^{has an} improved ~~in its~~ mounting reliability and ~~which~~ has external terminals formed by exposing portions of leads from a back surface of a resin sealing member. End portions on one side of the leads are fixed to a back surface of a semiconductor chip, and portions of the leads positioned outside the semiconductor chip are connected with electrodes formed on the semiconductor chip through wires.